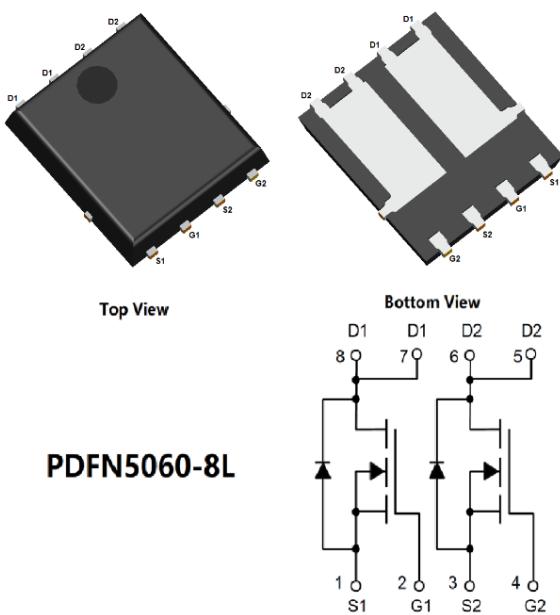


N-Channel Enhancement Mode Field Effect Transistor



PDFN5060-8L

Product Summary

NMOS(Die1/Die2)

- V_{DS} 40V
- I_D 60A
- $R_{DS(ON)}$ (at $V_{GS}=10V$) <7.7mohm

General Description

- High density cell design for low $R_{DS(ON)}$
- High Speed switching
- Moisture Sensitivity Level 1
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free
- Part no. with suffix "Q" means AEC-Q101 qualified

Applications

- DC-DC Converters
- Power management functions
- Industrial and Motor Drive application
- 12V Automotive systems

■ Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	N-Die1/Die2	Unit
Drain-source Voltage	V_{DS}	40	V
Gate-source Voltage	V_{GS}	± 20	V
Drain Current	$T_c=25^\circ C$	I_D	A
	$T_c=100^\circ C$		
	$T_A=25^\circ C$		
	$T_A=100^\circ C$		
Pulsed Drain Current ^A	I_{DM}	220	A
Avalanche energy ^B	E_{AS}	64	mJ
Total Power Dissipation ^C	$T_c=25^\circ C$	P_D	W
	$T_c=100^\circ C$		
	$T_A=25^\circ C$		
	$T_A=100^\circ C$		
Junction and Storage Temperature Range	T_J, T_{STG}	-55~+175	°C

■ Thermal resistance

Parameter	Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient ^D	$R_{\theta JA}$	50	60	°C/W
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	1.9	2.3	



■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJGD60G04HJQ	F1	YJGD60G04HJ	5000	10000	100000	13" reel

■ NMOS(Die1/Die2) Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	40			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=40\text{V}, V_{\text{GS}}=0\text{V}$			1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}= \pm 20\text{V}, V_{\text{DS}}=0\text{V}$			± 100	nA
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	2.0	2.6	4.0	V
Static Drain-Source On-Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=20\text{A}$		5.9	7.7	$\text{m}\Omega$
Diode Forward Voltage	V_{SD}	$I_{\text{s}}=20\text{A}, V_{\text{GS}}=0\text{V}$		0.9	1.3	V
Gate Resistance	R_g	$f=1\text{MHz}$		1.1		Ω
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$		915		pF
Output Capacitance	C_{oss}			320		
Reverse Transfer Capacitance	C_{rss}			42		
Switching Parameters						
Total Gate Charge	Q_g	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=20\text{V}, I_{\text{D}}=30\text{A}$		17.2		nC
Gate-Source Charge	Q_{gs}			3.6		
Gate-Drain Charge	Q_{gd}			7.18		
Reverse Recovery Charge	Q_{rr}	$I_{\text{F}}=30\text{A}, di/dt=100\text{A/us}$		27.25		ns
Reverse Recovery Time	t_{rr}			41.12		
Turn-on Delay Time	$t_{\text{D(on)}}$			7.3		
Turn-on Rise Time	t_r	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=20\text{V}, I_{\text{D}}=30\text{A}$ $R_{\text{GEN}}=2.2\Omega$		174.9		ns
Turn-off Delay Time	$t_{\text{D(off)}}$			15.7		
Turn-off fall Time	t_f			3.17		

- A. Repetitive rating; pulse width limited by max. junction temperature.
- B. $V_{\text{DD}}=30\text{V}$, $R_g=25\Omega$, $L=2\text{mH}$, $I_{\text{AS}}=8\text{A}$.
- C. P_d is based on max. junction temperature, using junction-case thermal resistance.
- D. The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz. Copper, in the still air environment with $T_A=25^\circ\text{C}$.
The maximum allowed junction temperature of 175°C . The value in any given application depends on the user's specific board design.



■Typical Electrical and Thermal Characteristics Diagrams

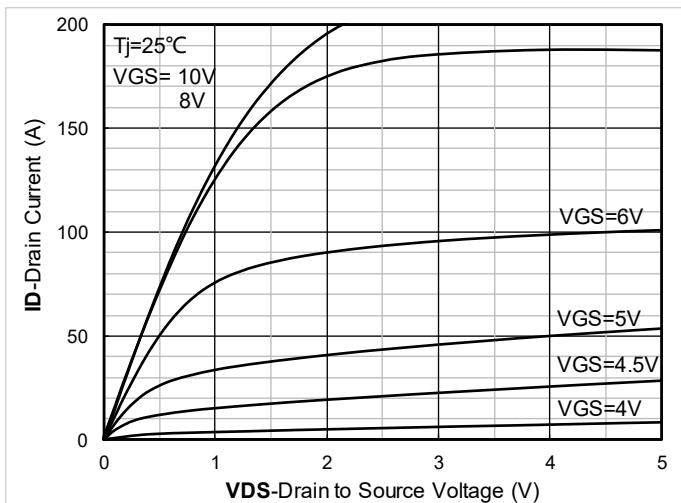


Figure 1. Output Characteristics

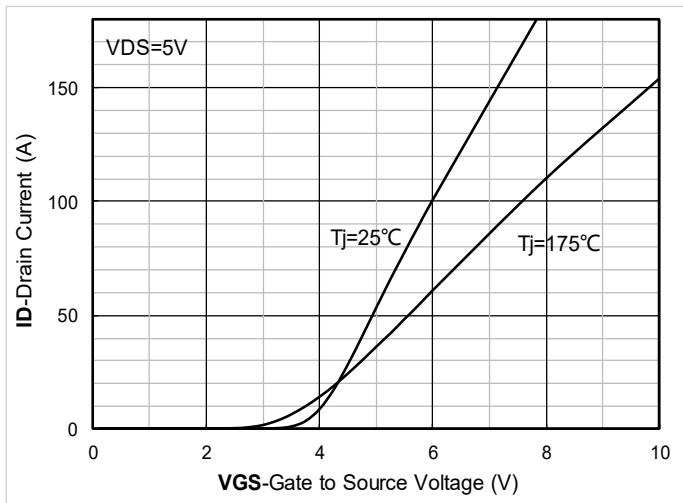


Figure 2. Transfer Characteristics

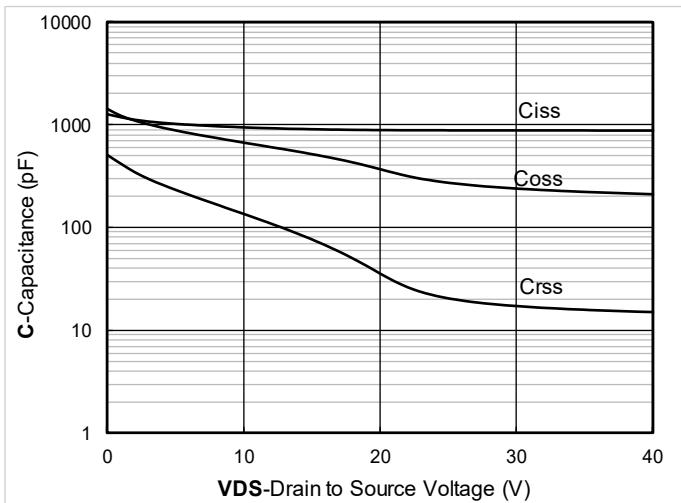


Figure 3. Capacitance Characteristics

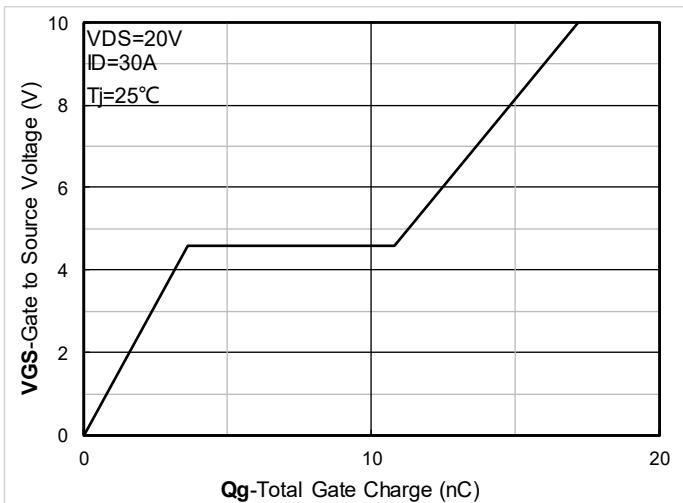


Figure 4. Gate Charge

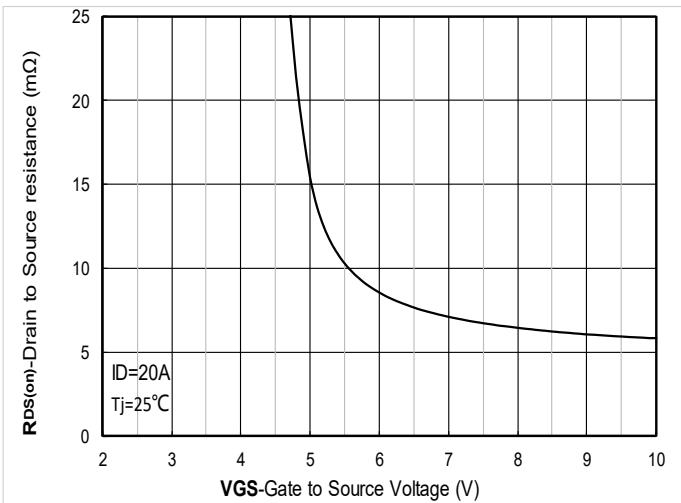


Figure 5. On-Resistance vs Gate to Source Voltage

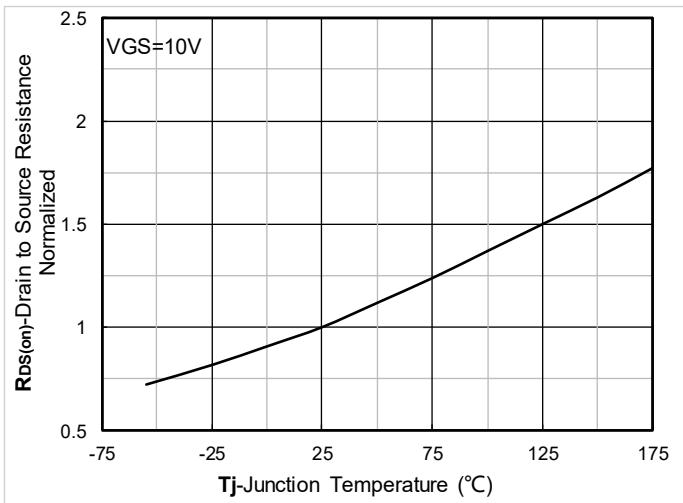


Figure 6. Normalized On-Resistance

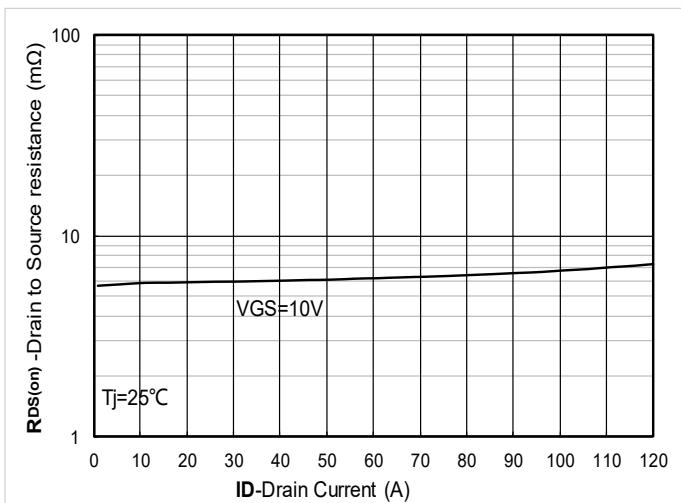


Figure 7. $R_{DS(on)}$ VS Drain Current

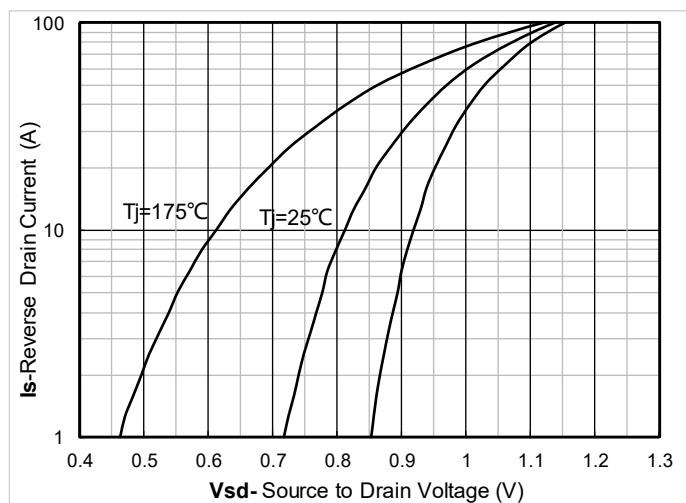


Figure 8. Forward characteristics of reverse diode

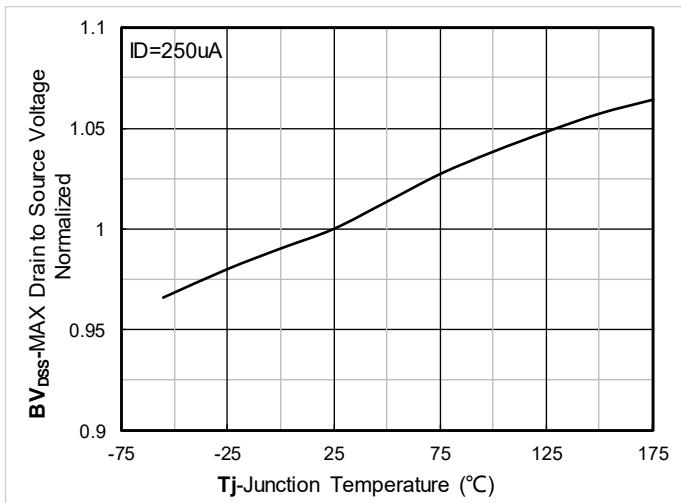


Figure 9. Normalized breakdown voltage

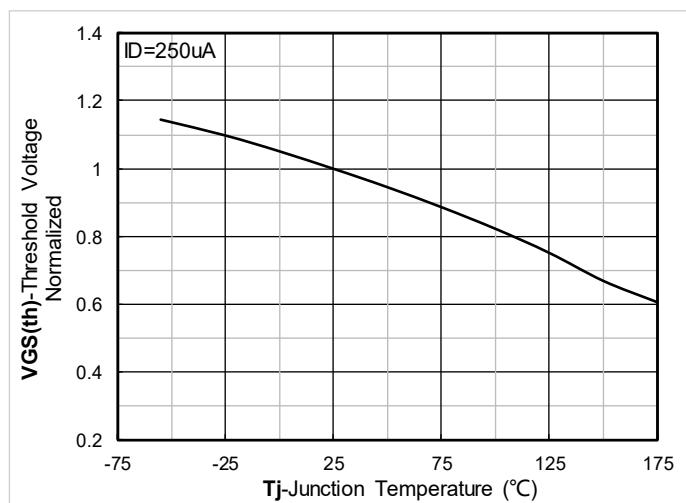


Figure 10. Normalized Threshold voltage

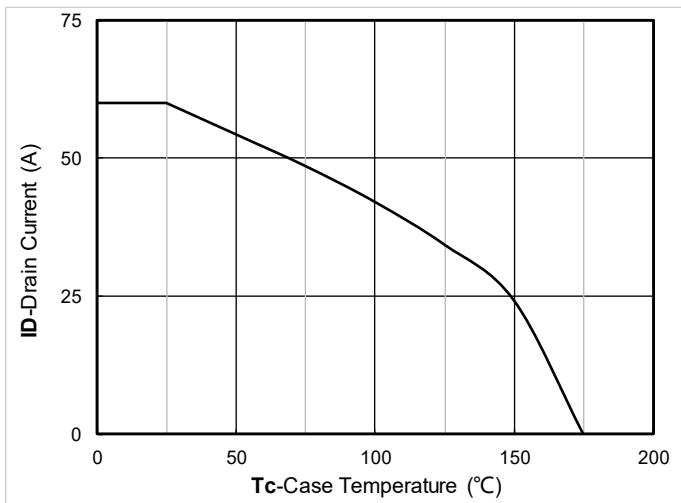


Figure 11. Current dissipation

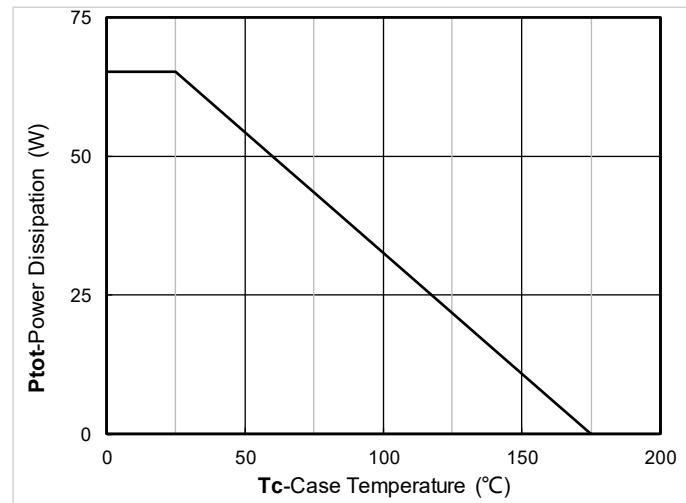


Figure 12. Power dissipation

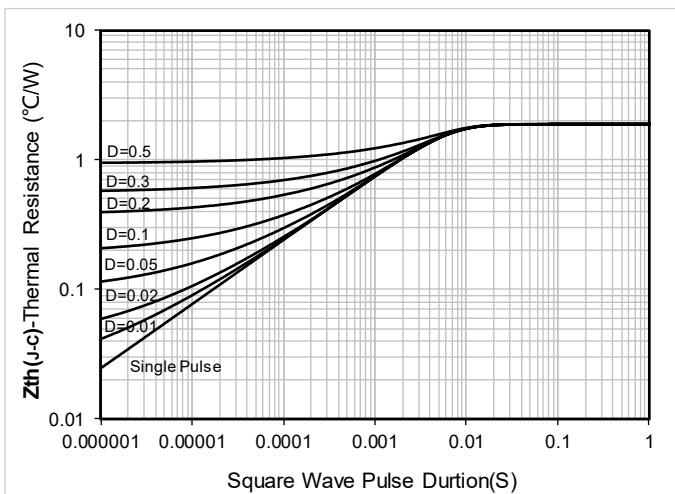


Figure 13. Maximum Transient Thermal Impedance

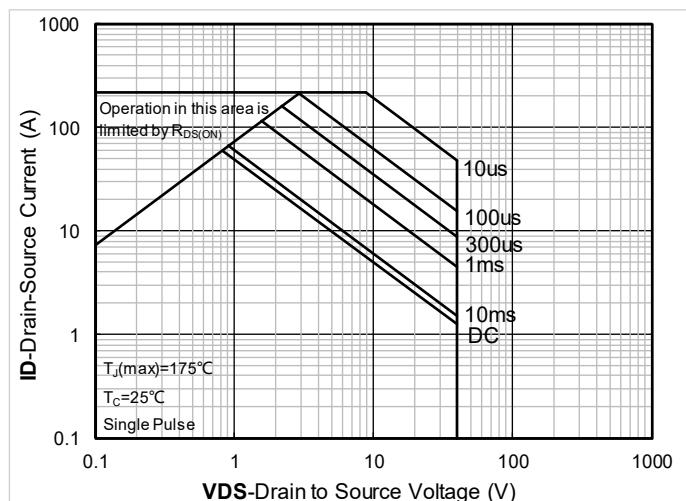
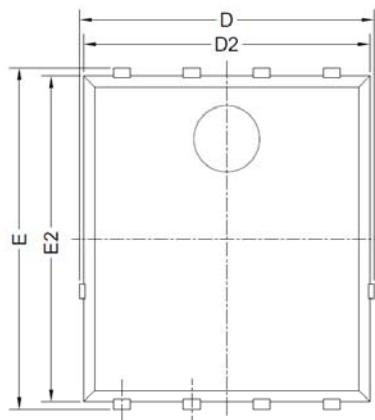
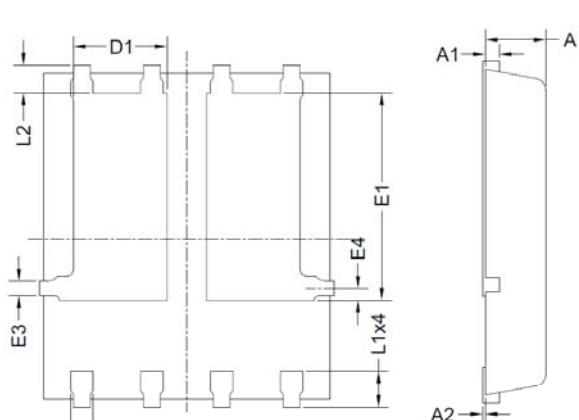
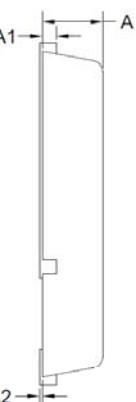
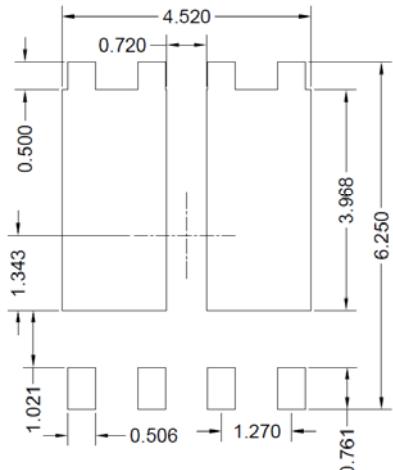


Figure 14. Safe Operation Area



■ PDFN5060-8L Package information

Top View
正面视图Bottom View
背面视图Side View
侧面视图Suggested Solder Pad Layout
Top View

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
D	5.15	5.35	5.55
E	5.95	6.15	6.35
A	1.00	1.10	1.20
A1	0.254 BSC		
A2			0.10
D1	1.50	1.70	1.90
E1	3.52	3.72	3.92
D2	5.00	5.20	5.40
E2	5.66	5.86	6.06
E3	0.254REF		
E4	0.21REF		
L1	0.56	0.66	0.76
L2	0.50 BSC		
b	0.31	0.41	0.51
e	1.27 BSC		

Note:

1. Controlling dimension:in millimeters.
2. General tolerance: $\pm 0.10\text{mm}$.
3. The pad layout is for reference purposes only.



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